

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	1322	(substrate material) and (((metal adj (film layer)) cr chromium titanium ti tungsten w wolfram palladium pd molybdenum mo) and (((second adj (metal adj (film layer))) al aluminum copper cu gold au silver ag) with (pattern pattern\$3)) and ((positive adj electrode) (anode adj (plate mesh)) anode) and (((acid acid\$3) adj (electrolyte solution)) ((hydrochloric sulfuric carboxylic hydrofluoric phosphoric orthophosphoric) adj acid) HCl H2SO4 H2CO3 CH3COOH C2O2H4 HF H3PO4) and ((reduction reduc\$3 remov\$3) with ((passivation passivat\$3 oxidiz\$3 oxidation oxide) near3 (layer film cr chromium titanium ti tungsten w wolfram palladium pd molybdenum mo)) and (etch etch\$3 polish polish\$3))	US-PGPUB; USPAT; USOOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/05 13:04
S3	697	(substrate material) and (((etch etch\$3 polish polish\$3) with ((metal adj (film layer)) cr chromium titanium ti tungsten w wolfram palladium pd molybdenum mo)) and (((second adj (metal adj (film layer))) al aluminum copper cu gold au silver ag) with (pattern pattern\$3)) and ((positive adj electrode) (anode adj (plate mesh)) anode) and (((acid acid\$3) adj (electrolyte solution)) ((hydrochloric sulfuric carboxylic hydrofluoric phosphoric orthophosphoric) adj acid))	US-PGPUB; USPAT; USOOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/05 13:25

		HO H2SO4 H2003 CH3COOH C202H4 HF H3PO4) and ((reduction reduc\$3 remov\$3) with ((passivation passivat\$3 oxidiz\$3 oxidation oxide) near3 (layer film cr chromium titanium ti tungsten w wolfram palladium pd molybdenum (mo)))				
S4	76	(substrate material) and ((etch etch\$3 polish polish \$3) with ((metal adj (film layer)) cr chromium titanium ti tungsten w wolfram palladium pd molybdenum mo)) and (((second adj (metal adj (film layer))) al aluminum copper cu gold au silver ag) with (pattern pattern \$3)) and (((acid acid\$3) adj (electrolyte solution)) ((hydrochloric sulfuric carboxylic hydrofluoric phosphoric orthophosphoric) adj acid) HCl H2SO4 H2003 CH3COOH C202H4 HF H3PO4) and ((positive adj electrode) (anode adj (plate mesh)) anode) same ((reduction reduc\$3 remov \$3) with ((passivation passivat\$3 oxidiz\$3 oxidation oxide) near3 (layer film cr chromium titanium ti tungsten w wolfram palladium pd molybdenum mo)))	US-PGPUB; USPAT; USOOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/05 13:27
S5	19	("2250556" "2931760" "3915809" "4350564" "5294326" "5425822"). PN.	US-PGPUB; USPAT; USOOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/05 16:09
S6	1637	(chromium cr titanium ti tungsten w palladium pd molybdenum mo) and (205/640-686.ccls.)	US-PGPUB; USPAT; USOOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/12 15:07

S7	2	"20040035717".pn.	US-PPGPUB; USPAT; USOOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/12 16:45
S8	590	((chromium cr titanium ti tungsten w palladium pd molybdenum mo) and (205/640-686.cds.) and (pattern pattern\$3))	US-PPGPUB; USPAT; USOOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/12 17:08
S9	84	((chromium cr titanium ti tungsten w palladium pd molybdenum mo) with (pattern pattern\$3)) and (205/640-686.cds.)	US-PPGPUB; USPAT; USOOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/12 17:11
S10	69	((chromium cr titanium ti tungsten w palladium pd molybdenum mo) with (pattern pattern\$3)) and (205/640-686.cds.) and (@ad<"20020821" @pd<"20020821")	US-PPGPUB; USPAT; USOOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/12 17:12
S11	17	(((chromium cr titanium ti tungsten w palladium pd molybdenum mo) near (layer film)) with (pattern pattern\$3)) and (205/640-686.cds.) and (@ad<"20020821" @pd<"20020821")	US-PPGPUB; USPAT; USOOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/12 17:13

3/ 13/ 2008 8:48:10 AM

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